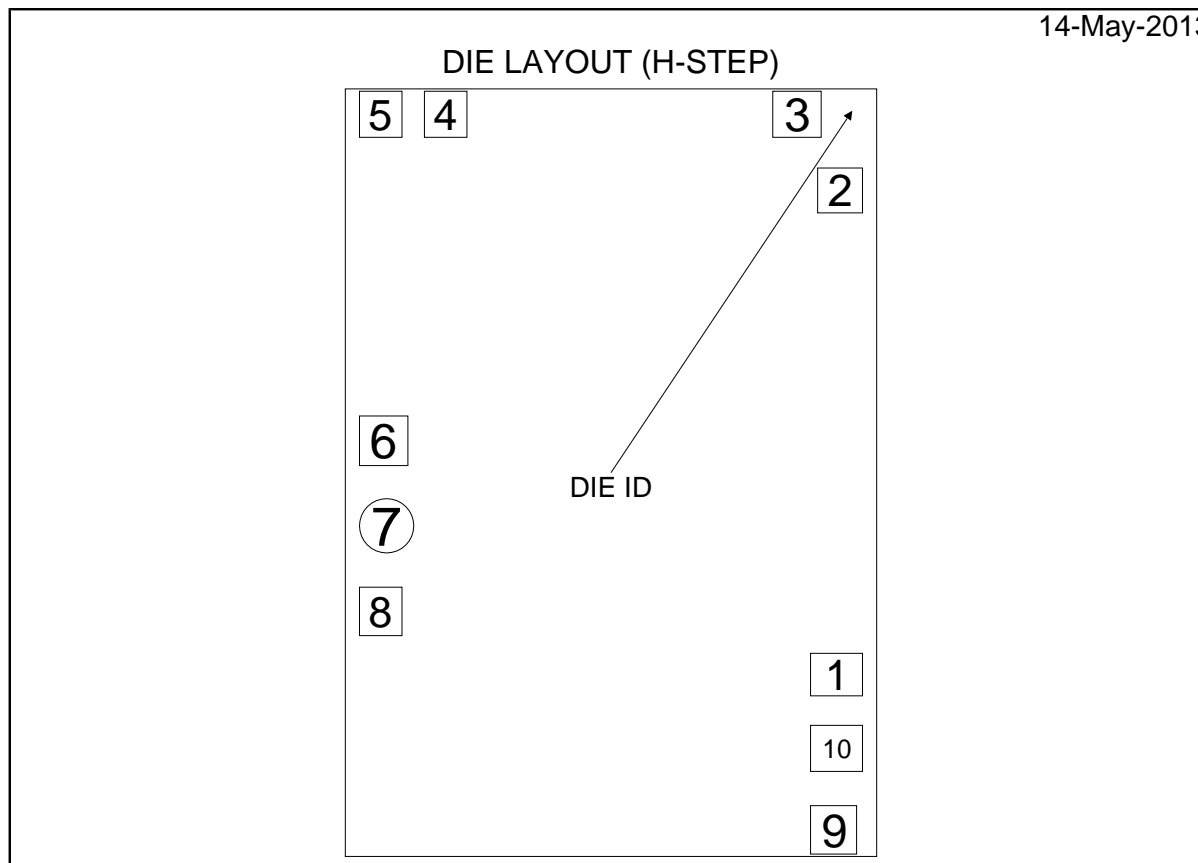


LM111-MDE
VOLTAGE COMPARATOR

14-May-2013



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	111H	Bond Pad Opening Size (min)	91.44µm x 99.06µm
Die Step	H	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	152.4mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1143.00µm x 1651.00µm 45.0mils x 65.0mils	Back Side Connection	Floating
Thickness	304.8µm Nominal		
Min Pitch	139.70µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(H-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
GND	1	485.14	-434.34	111.76	x	91.44
INPUT +	2	492.76	607.06	96.52	x	96.52
INPUT -	3	400.05	770.89	104.14	x	99.06
V-	4	-355.60	770.89	91.44	x	99.06
Balance	5	-495.30	770.89	91.44	x	99.06
Balance/Strobe	6	-488.95	68.58	104.14	x	106.68
NC	7	-482.60	-114.30	116.84	x	116.84
NC	8	-495.30	-298.45	91.44	x	104.14
OUTPUT	9	478.79	-768.35	99.06	x	104.14
V+	10	485.14	-593.09	111.76	x	99.06

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Notes

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